REMARKS

A power of attorney will be filed shortly after the filing of this Amendment.

It is believed that the objection to the claims as being indefinite and functional or containing operational language is corrected in the new claims submitted herewith. However, if any objections are found in the claim language, they will promptly be corrected upon the Examiner pointing out such informalities.

All of the previous claims were rejected as anticipated by or obvious over Kishi and particularly Fig. 5 and col. 5, lines 15-44. We would point out to the Examiner, with reference to Kishi, that the torque motor 13 shown in the drawings does not cause rotation of wafer 1. The function of the motor as defined in col. 4, lines 15-23, is to drive a gear assembly (14*a* and 14*b*) so that the wafer 1 supported by head 16 is forcibly brought into contact with an O ring 8 provided in the opening 5 of the treatment tank 3. In other words, motor 13 does not rotate the wafer, it forces the wafer against O ring 8. It is the exact opposite of rotating the wafer relative to the treatment tank 3.

Kishi approaches the problem of non-uniform electroplating by treating the bubbles which accumulate on the wafer. Kishi's solution to the problem is to place the wafers vertically, thus allowing the bubbles to escape. However, the main cause of non-uniformity is the resistivity of the thin layer on the wafer. Thus applicants and Kishi attack the problem of non-uniformity of electroplating from quite different angles.

The structure now set forth in claim 19 provides a formula for a plating parameter which involves the resistivities of the metal to be plated and the electrolyte and involves the radius of the wafer, the thickness of the metal and the distance between the wafer and the counter electrode. Claim 19 also states that $B^2 \leq 1$.

Reconsideration of the reference Kishi is requested.

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The Examiner also requested an abstract. Such an abstract is attached.

The Examiner kindly indicated in the last Office Action that claim 9 would be allowable if rewritten to overcome informalities because the references of record do not show or suggest electroplating apparatus in which a rotating distributer is adapted for placement in front of a supported wafer, such that holes drilled in the distributer cause electrolyte to flow at an angle. This indication of allowance is appreciated. However, it is believed, as brought forth in the other claims submitted herewith, that there are other features of the invention which are also of patentable nature.

Claims remaining in this application are 19-38. Allowance is believed to be in order and such action is earnestly solicited.

Respectfully submitted,

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